

28/4



IN THE UNITED STATES  
PATENT AND TRADEMARK OFFICE

PATENT APPLICATION

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**CASE:** 60-40-1-1

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**TITLE:** STACKED MODULE PACKAGE

**SERIAL NO.** 09/964,009

**GROUP ART UNIT** 2814

**FILING DATE** 09/14/00

**EXAMINER** DiLinh P. Nguyen

**COMMISSIONER FOR PATENTS**  
**ALEXANDRIA, VA 22313-1450**

**SIR:**

In response to the Office action mailed 07/18/03 please amend the above referenced application as follows:

In the claims:

Claims 1-22 canceled.

23. (currently amended) A The stacked MCM package of claim 22  
wherein a the digital MCM is mounted on a digital MCM substrate and the  
an RF MCM is mounted on an RF MCM substrate, the stacked MCM  
package further comprising: